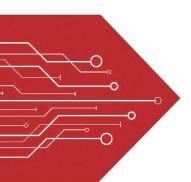
MSKSEMI















ESD

TVS

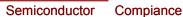
TSS

MOV

GDT

PLED

Broduct data sheet









S0D-123FL



Applications

General rectification

Features

- Small power mold type. (PMDU)
- Low I_R.
- High reliability

Construction

Silicon epitaxial planer

Absolute maximum ratings (Ta=25°C)

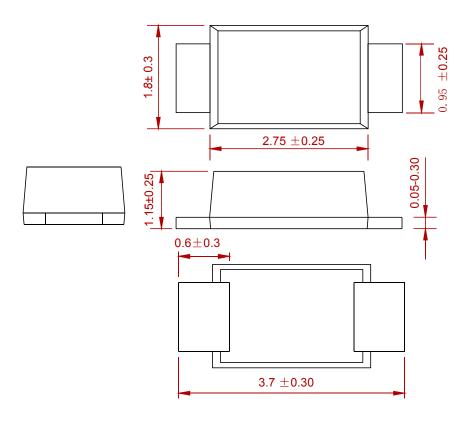
Parameter	Symbol	Limits	Unit
Reverse voltage (repetitive peak)	V _{RM}	30	V
Reverse voltage (DC)	V _R	30	V
Average rectified forward current	lo	1	Α
Forward current surge peak (60Hz / 1cyc)	I _{FSM}	30	Α
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-40 to +125	°C

^(*1)Mounted on epoxy board. 180° Half sine wave

Electrical characteristic (Ta=25°C)

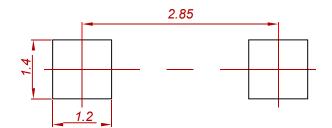
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V _F 1	-	0.39	0.46	V	I _F =0.5A
	V _F 2	-	0.43	0.48	V	I _F =1.0A
Reverse current	I _R 1	-	3.0	20	μΑ	V _R =15V
	I _R 2	-	9.0	50	μΑ	V _R =30V

PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
RB160M-30	SOD-123FL	3000



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